



3D Packaging and Integration Japan TC Chapter

Meeting Summary and Minutes

Japan Standards Winter 2021 Meeting

May 28, 2021, 14:00-17:00

Web conference

TC Chapter Announcements

Next TC Chapter Meeting

Friday, October 22, 2021, 14:00-17:00

Web

Table 1 Meeting Attendees

Italics indicate virtual participants

Co-Chairs: Kazunori Kato (AiT), Masahiro Tsuruya (iNEMI), Haruo Shimamoto (AIST)

SEMI Staff: Mami Nakajo

<i>Company</i>	<i>Last</i>	<i>First</i>	<i>Company</i>	<i>Last</i>	<i>First</i>
<i>AIST</i>	<i>Shimamoto</i>	<i>Haruo</i>	<i>Hitachi Power Solutions</i>	<i>Ohno</i>	<i>Shigeru</i>
<i>AiT</i>	<i>Kato</i>	<i>Kazunori</i>	<i>Nidec-Read</i>	<i>Miyazaki</i>	<i>Yoko</i>
<i>Mitsui Chemicals, Inc</i>	<i>Yamamoto</i>	<i>Yugo</i>	<i>Shin-Etsu Polymer</i>	<i>Shida</i>	<i>Hiroyuki</i>
<i>Panasonic</i>	<i>Kato</i>	<i>Takeshi</i>	<i>Marubeni Plax</i>	<i>Igeta</i>	<i>Yasuo</i>
<i>Retired</i>	<i>Takahashi</i>	<i>Mark</i>	<i>Advantest Corporation</i>	<i>Ishikawa</i>	<i>Takaji</i>
<i>iNEMI</i>	<i>Tsuruya</i>	<i>Masahiro</i>	<i>KOKUSAI ELECTRIC</i>	<i>Matsuda</i>	<i>Mitsuhiro</i>
			<i>SEMI Japan</i>	<i>Nakajo</i>	<i>Mami</i>

Table 2 Leadership Changes

<i>WG/TF/SC/TC Name</i>	<i>Previous Leader</i>	<i>New Leader</i>
None		

Table 3 Committee Structure Changes

<i>Previous WG/TF/SC Name</i>	<i>New WG/TF/SC Name or Status Change</i>
Thin Chip Handling Task Force	Disband

Table 4 Ballot Results

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
6703	Revision to SEMI G63-95 (Reapproved 0811) "Test Method for Measurement of Die Shear Strength"	Failed due to insufficient rate and return to TF for rework

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 5 Activities Approved by the GCS between meetings of the TC Chapter

#	Type	SC/TF/WG	Details
None			

Table 6 Authorized Activities

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

#	Type	SC/TF/WG	Details
None			

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:

<http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF>

Table 7 Authorized Ballots

#	When	TF	Details
6703A	08/09-2019	3D Packaging & Integration 5 Year Review Task Force	Revision of SEMI G63-95 (Reapproved 0811) TEST METHOD FOR MEASUREMENT OF DIE SHEAR STRENGTH

Table 8 SNARF(s) Granted a One-Year Extension

#	TF	Title	Expiration Date
None			

Table 9 SNARF(s) Abolished

#	TF	Title
None		

Table 10 Standard(s) to receive Inactive Status

Standard Designation	Title
SEMI G75-0698(Reapproved 0615)	Standard Test Method of the Properties of Leadframe Tape
SEMI G70-0996 (Reapproved 0811)	Standard for Equipment and Leadframe Fixtures for Measurement of Plastic Package Leadframes

Table 11 New Action Items

Item #	Assigned to	Details
20210528-01	SEMI Staff	To request that NA Staff inform the schedule of the next NA 3D TC Chapter meeting.
20210528-02	SEMI Staff	To confirm the schedule and contents of the new SNARF for CMP stands in Middle End Process Task Force which is mentioned in Taiwan Liaison Report.
20210528-03	5-year review TF leader & SEMI Staff	To prepare the latest 5 year review list by the next TC meeting.

Table 11 New Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
20210528-04	5 year review TF	To revise the SNARF of G13 and prepare for the ballot by the next TC meeting.

Table 12 Previous Meeting Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
20210118-01	Co-Chairs	To review SEMI-G13,G70,and G75 and to propose the next step for the document by the next 3DP&I Japan TC Chapter meeting to held in 2021 spring> Closed

1 Welcome, Reminders, and Introductions

Kazunori Kato (AiT) called the meeting to order at 14:00. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: 01-02_Required Element Nov 2020 Rev1_E+J_r1 ,

2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

Motion:	To approve the previous meeting minutes of the 3D Packaging & Integration Japan TC Chapter on January 18, 2021.
By / 2nd:	Mitsuhiro Matsuda (KOKUSAI ELECTRIC) / Hiroyuki Shida (Shin-Etsu Polymer)
Discussion:	None
Vote:	11 in favor and 0 opposed. Motion passed.

Attachment: 02-01_20210118_3DPI-Japan_MeetingMinutes_final ,

3 Liaison Reports

3.1 3D Packaging & Integration North America TC Chapter

Mami Nakajo (SEMI Japan) reported the 3D Packaging & Integration North America TC Chapter activity status based on the report as attached.

Action Item 20210528-01: SEMI Staff : To request that NA Staff inform the schedule of the next NA 3D TC Chapter meeting.

Attachment: 03-01_NA 3DP&I Liaison Report March2021 v1 ,

3.2 3D Packaging & Integration Taiwan TC Chapter

Mami Nakajo (SEMI Japan) reported the 3D Packaging & Integration Taiwan TC Chapter activity status based on the report as attached.

Action Item 20210528-02: SEMI Staff : To confirm the schedule and contents of the new SNARF for CMP stands in Middle End Process Task Force which is mentioned in Taiwan Liaison Report

Attachment: 03-02_ 3D P&I TW Liaison Report_20210302,

3.3 SEMI Staff Report

Mami Nakajo (SEMI) explained the SEMI Staff Report based on the report as attached.

Attachment: 03-03_ Staff Report March 2021_v2_Update_20210609add ,

4 Ballot Review

NOTE 1: TC Chapter adjudication on ballots reviewed is detailed in the Audits & Review (A&R) Subcommittee Forms for procedural review. The A&R forms are available as attachments to these minutes. The attachment number for each balloted document is provided under each ballot review section below.

4.1 Document #6703, Revision to SEMI G63-95 (Reapproved 0811) “Test Method for Measurement of Die Shear Strength”

- Failed due to insufficient rate and return to TF for rework

5 Subcommittee and Task Force Reports

5.1 GCS Report

Kazunori Kato (AiT) reported there is no activities by the GCS between meetings of the TC Chapter.

5.2 3D Packaging & Integration 5 Year Review Task Force

Masahiro Tsuruya (iNEMI) reported the 3D Packaging & Integration 5 Year Review Task Force status as attached.

Attachment: 05-02_TF Report 1.1 - 5yrs Review TF v202105

5.3 3DS IC Bonded Layer Inspection Metrology Task Force

Shigeru Ohno (Hitachi Power Solutions) reported 3DS IC Bonded Layer Inspection Metrology Task Force status as attached.

Attachment: 05-03_ActivitiesReport_3DSIC-InspectionTF_20210528

5.4 450mm Assembly and Test Die Preparation Task Force

Mami Nakajo (SEMI Japan) reported on behalf of Sumio Masuchi (DISCO), there is no update.

Kazunori Kato (AiT) addressed that he and Sumio Masuchi (DISCO) will discuss the status of this TF will be inactive or disband.

5.5 Encapsulation Characteristics for Wafer Level Package and Panel Level Packaging Task Force

Masahiro Tsuruya (iNEMI) reported the status of Encapsulation Characteristics for Wafer Level Package and Panel Level Packaging Task Force as attached.

Attachment: 05-05_ TF Report 1.4 - PLP Encapsulation Characteristic TF v202105

5.6 Panel Level Packaging (PLP) Glass Carrier Task Force

Mark Takahashi (retired) reported the Panel Level Packaging Task Force status as attached.

Attachment: 05-06_PLP Glass Carrier TF Status_20210528

5.7 Thin Chip Handling Task Force

Haruo Shimamoto (AIST) requested to disband the TFOF since its scope and the current technological trends have shifted.

Motion:	To disband the TFOF* Thin Chip Handling Task Force *
By / 2nd:	Haruo Shimamoto (AIST) / Mitsuhiro Matsuda (KOKUSAI ELECTRIC)
Discussion:	None
Vote:	11 in favor and 0 opposed. Motion passed.

5.8 3D Packaging & Integration Steering Group

Masahiro Tsuriya (iNEMI) reported there is no update and the next meeting will be held around November or December this year.

6 Old Business

6.1 Project period Review

No update

6.2 5-Year Review

Action will be taken at the next committee meeting.

Action Item 20210528-03: 5-year review TF leader & SEMI Staff: to prepare the latest 5 year review list by the next TC meeting.

7 New Business

7.1 New SNARFs Authorization

None

7.2 New Ballots Authorization

7.2.1 Proposal for Revision to SEMI G63-95

- Document #6703A: SNARF for: Revision to SEMI G63-95 (Reapproved 0811) “Test Method for Measurement of Die Shear Strength”
 - Submitted by 3D Packaging & Integration 5 Year Review TF

Haruo Shimamoto (AIST) addressed the TC Chapter on this topic.

Motion:	To authorize the ballot submission of document#6703A Revision to SEMI G63-95 (Reapproved 0811) “Test Method for Measurement of Die Shear Strength” for Cycle 8 or 9, 2021
By / 2nd:	Haruo Shimamoto (AIST) / Mitsuhiro Matsuda (KOKUSAI ELECTRIC)
Discussion:	None
Vote:	11 in favor and 0 opposed. Motion passed.

7.3 Review of G13,G70,and G75

Kazunori Kato (AiT) reported the following documents.

Co-Chairs reviewed these documents and decided the following documents for Inactive.



- SEMI G70-0996, Standard for Equipment and Leadframe Fixtures for Measurement of Plastic Package Leadframes
- SEMI G75-0698, Standard Test Method of the Properties of Leadframe Tape

Regarding of the following document, action will be taken at the next committee meeting.

- SEMI G13-88, Standard Test Method for Expansion Characteristics of Molding Compounds

Action Item 20210528-04: 5-year review TF to revise the SNARF of G13 and prepare for the ballot by the next TC meeting.

8 Action Item Review

8.1 Open Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
20210118-01	Co-Chairs	To review SEMI-G13,G70,and G75 and to propose the next step for the document by the next 3DP&I Japan TC Chapter meeting to held in 2021 spring> Closed

8.2 New Action Items

The TC Chapter reviewed the following new action item.

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
20210528-01	SEMI Staff	To request that NA Staff inform the schedule of the next NA 3D TC Chapter meeting.
20210528-02	SEMI Staff	To confirm the schedule and contents of the new SNARF for CMP stands in Middle End Process Task Force which is mentioned in Taiwan Liaison Report
20210528-03	5-year review TF leader & SEMI Staff	To prepare the latest 5year review list by the next TC meeting.
20210528-04	5year review TF	To revise the SNARF of G13 and prepare for the ballot by the next TC meeting.

9 Next Meeting and Adjournment

The next meeting is scheduled for Friday, October 22, 2021, 14:00-17:00 Web

See <http://www.semi.org/standards-events> for the current list of events.

Having no further business, a motion was made to adjourn. Adjournment was at 17:00.



Respectfully submitted by:

Mami Nakajo

Coordinator

SEMI Japan

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Minutes tentatively approved by:

Kazunori Kato (AiT), Co-chair	June, 10, 2021
Masahiro Tsuruya (iNEMI), Co-chair	June, 10, 2021
Haruo Shimamoto (ASIT), Co-chair	June, 10, 2021

Table 13 Index of Available Attachments^{#1}

<i>Title</i>	<i>Title</i>
01-02_Required Element Nov 2020 Rev1_E+J_r1	05-03_ActivitiesReport_3DSIC-InspectionTF_20210528
02-01_20210118_3DPI-Japan_MeetingMinutes_final	05-05_TF Report 1.4 - PLP Encapsulation Characterisitic TF v202105
03-01_NA 3DP&I Liaison Report March2021 v1	05-06_PLP Glass Carrier TF Status_20210528
03-02_3D P&I TW Liaison Report_20210302	
03-03_Staff Report March 2021_v2_Update_20210609add	
05-02_TF Report 1.1 - 5yrs Review TF v202105	

^{#1} Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.